

ABSTRACT OF THE DISCLOSURE

The present invention provides a following housing for electronic equipment. The housing has a metal board having an adhesive layer to which one or more components are attached. In the housing, at least one of the components is formed on a surface of the metal board opposite a gate for injection molding by injecting a molding material through a through hole previously pierced in the metal board. The component has an appearance on a side of the housing opposite the gate for injection molding. Further, in the housing, at least one portion of the metal board at a side wall thereof has a convex shape.

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